

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-218. (Canceled)

219. (Currently amended) A chip package comprising:

a substrate;

only one die having a top surface at a first horizontal level higher than a second horizontal level of a top surface of said substrate, wherein said substrate has no portion at said first horizontal level;

an adhesive material joining said top surface of said substrate and a bottom surface of said only one die;

a first insulating layer over said first horizontal level, said only one die and said substrate and across an edge of said only one die, wherein said first insulating layer comprises a first portion vertically over said only one die and a second portion not vertically over said only one die, wherein said first insulating layer is not integrated with said adhesive material;

a patterned circuit layer over said first insulating layer, said first horizontal level, said only one die and said substrate and across said edge, wherein said patterned circuit layer is connected to said only one die through a first opening in said first insulating layer;

~~an inductor~~ a passive device over said first horizontal level and said first insulating layer, wherein said passive device comprises an inductor; and

a second insulating layer ~~[[on]]~~ over said inductor ~~passive device~~.

220. (Previously presented) The chip package of claim 219, wherein said only one die comprises a first trace formed therein, and wherein said patterned circuit layer comprises a second trace having a thickness greater than that of said first trace.

221. (Previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a power bus.

222. (Previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a ground bus.

223. (Previously presented) The chip package of claim 219, wherein said patterned circuit layer connects multiple portions of said only one die.

Claims 224-227 (Canceled)

228. (Previously presented) The chip package of claim 219, wherein said first insulating layer comprises polyimide.

Claims 229-231 (Canceled)

232. (Previously presented) The chip package of claim 219, wherein said first insulating layer comprises benzocyclobutene (BCB).

Claims 233-235 (Canceled)

236. (Previously presented) The chip package of claim 219, wherein said adhesive material comprises a conductive paste joining said top surface of said substrate and said bottom surface of said only one die.

Claim 237 (canceled)

238. (Previously presented) The chip package of claim 219, wherein said adhesive material comprises an adhesive tape joining said top surface of said substrate and said bottom surface of said only one die.

239. (Previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises an electroplated metal.

240. (Previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a sputtered metal.

241. (Currently amended) The chip package of claim 219, wherein said ~~inductor~~ passive device has a portion vertically over said substrate but not vertically over said only one die.

242. (Previously presented) The chip package of claim 219 further comprising a metal bump having a portion vertically over said substrate but not vertically over said only one die.

Claims 243-250. (Canceled)

251. (Previously presented) The chip package of claim 219, wherein said second portion of said first insulating layer is vertically over said substrate.

Claims 252-256 (canceled)

257. (Currently amended) The chip package of claim 219 further comprising a polymer layer on said substrate, wherein said only one die is [[in]]between a first portion of said polymer layer and a second portion of said polymer layer.

Claim 258 (Canceled)

259. (Previously presented) The chip package of claim 257, wherein said polymer layer comprises epoxy.

260. (Previously presented) The chip package of claim 219 further comprising a solder bump over said first horizontal level.

Claim 261 (Canceled)

262. (Previously presented) The chip package of claim 219 further comprising a gold bump over said first horizontal level.

263. (Previously presented) The chip package of claim 219, wherein said only one die comprises multiple active devices, and said patterned circuit layer connects said multiple active devices.

264. (Previously presented) The chip package of claim 219, wherein said substrate comprises a silicon substrate.

265. (Previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises copper.

266. (Previously presented) The chip package of claim 219, wherein said substrate comprises a metal layer.

267. (Currently amended) The chip package of claim 219, wherein said ~~inductor~~ passive device comprises copper.